Issue date:

Kazuki Matsuo
Senior Manager

Resistor Business Division
General Purpose Device & Module Business Headquarters
ROHM Co., Ltd.

Notification of Product/Process Change

Doc. No.: 7026001

This letter intends as a formal notification of change to products which are currently supplied by ROHM Co., Ltd.

ROHM Co., Ltd. requires customers to provide acknowledgment of the receipt of this notification within 30 days from the date of this notice. Lack of acknowledgment of this notice within 30 days is considered as acceptance of the change.

After acknowledgement of the customer, lack of additional response within 90 day period constitutes acceptance of the change according to JEDEC Standard J-STD-046.

Your understanding and cooperation would be highly appreciated.

Issue Date: March 1, 2026

Title of change	Change of glass epoxy materials used in GMR series structural components (substrates)	
Affected product(s)	Manufacturer part number	Customer part number
	GMR50 HJx Series/GMR100 HJx Series/GMR320 HJx S	
Detailed description of change	Before	After
	Glass epoxy-based structural material	Switch to Equivalent Performance Substitute Material☐
Reason for change	Because the glass epoxy-based material, which is the structural material of the GMR series, has been discontinued by the manufacturer. This is because there is a need to switch to an alternative material with equivalent performance.	
Anticipated impact on quality	It has the same quality as the current product. At the time of this change, we have conducted process evaluation and reliability evaluation to confirm that there are no quality problems. (Please refer to the attached data for details.)	
Identification of change	The identification will be only the lot number	
Planned first ship date	#	Sample available schedule : Mar,1,2026
Comments	Continuous and stable supply by switching materials to ensure the obsolescence of structural materials in products	
Supplier contact	Please contact the local ROHM sales office or the authorized distributor.	
Notes		

ROHM SEMICONDUCTOR

Electronics for the Future

7026001
Change of glass epoxy materials used in GMR series structural components (substrates)

March 1st, 2026
General Purpose Devices & Module
Business Headquarters
Resistor Division

1．7026001 Overview

◆Target products

GMR50 HJx Series / GMR100 HJx Series / GMR320 HJx Series

◆Purpose / Background

Glass epoxy materials, which are the structural materials of the GMR series, have been discontinued by the material manufacturer. Switch to an alternative material with equivalent performance.

・When implementing this change, we conduct process evaluations and reliability evaluations to confirm that there are no quality problems.

※ Please refer to various data for details.

◆Changes

・ P4~P5 are listed.

◆Deadline for response: Saturday, October 31, 2026

2．7026001 Products to be changed

◆ GMR HJx Series

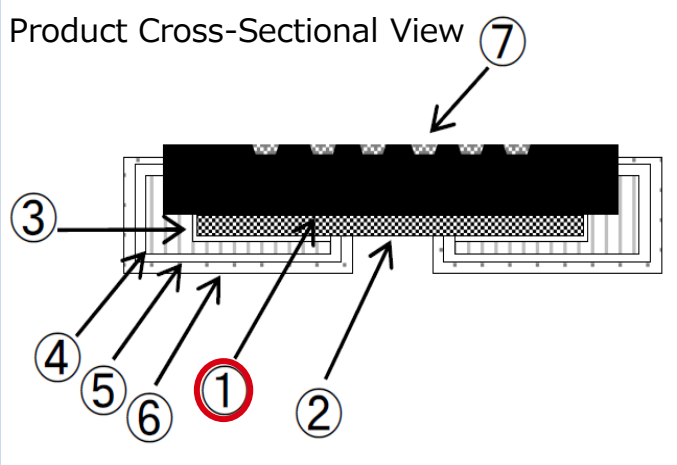
Products	P.N
GMR 50 series	GMR50HJAAFD
	GMR50HJBFA
	GMR50HJBFE
	GMR50HJBFG
	GMR50HJBFH
	GMR50HJBFI
	GMR50HJBFK
	GMR50HJBFM
	GMR50HJBFO
	GMR50HJBFQ
	GMR50HJBFW
	GMR50HJCFA
	GMR50HJCFE
	GMR50HJCFH
	GMR50HJCFI

Products	P.N
GMR 100 Series	GMR100HJAAFD
	GMR100HJAFT
	GMR100HJBAFA
	GMR100HJBAFB
	GMR100HJBDM
	GMR100HJBFA
	GMR100HJBFC
	GMR100HJBFE
	GMR100HJBFH
	GMR100HJBFI
	GMR100HJBFJ
	GMR100HJBFM
	GMR100HJBFO
	GMR100HJBFQ
	GMR100HJBFS
	GMR100HJBFT
	GMR100HJBFV
	GMR100HJCFA
	GMR100HJCFH
	GMR100HJCFI

Products	P.N
GMR 320 series	GMR320HJAAFD
	GMR320HJBFA
	GMR320HJCFA

There will be no change in the part number
Product identification will be Lot number

3. 7026001 Changes/4M

4M	Before the change	After the change
Man	–	No change
Machine	–	No change
Materials	Structural Material Glass Epoxy Substrate ① 	Structural Material Glass Epoxy Substrate Modification Materials for this change **No. / Parts / Materials** ① Substrate — Metal foil / glass epoxy ② Overcoat — Epoxy resin ③ Internal electrode — Silver thick film ④ Cu Plating — Copper ⑤ Ni Plating — Nickel ⑥ Sn Plating — Tin ⑦ Mark — - However, the board manufacturer remains unchanged
Method	QC process table compliant	No change
Management	–	No change

4. 7026001 Appearance/Characteristics

Items	Before the change	After the change
Exterior photo (Surface)		 The appearance and visibility of the markings do not change due to board changes
Exterior photo (Back)		
Product Dimensions	–	Same as conventional product (please refer to the page 6)
Electrical Characteristics	–	Same as conventional product (please refer to the page 6)
Mechanical Properties	–	Same as conventional product
Long-term reliability	–	Same as conventional products (please refer to the page 7)
Environmental Data		Some of the constituent substances will be changed (separately)

5. 7026001 Comparison

GMR50HJx

ROHM SEMICONDUCTOR | Products: High Power Metal Plate Shunt Resistors | Type: GMR50HJx Series

Confidential — GMR50 HJx series substrate material change_Comparison table — Different points

Type	GMR50 HJx Series (Present)	GMR50 HJx Series (After change)
Appearance	Top surface (marking side): R150; Bottom surface (electrode side)	Top surface (marking side): R150; Bottom surface (electrode side); The visibility of the markings has been improved.
Size	5025(2010) : mm(inch)	5025(2010) : mm(inch)
External Dimension : mm	10L0; L:5.00±0.25 W:2.50±0.25 a:2.05±0.25 b:0.90±0.25 t:0.40±0.15	10L0; L:5.00±0.25 W:2.50±0.25 a:2.05±0.25 b:0.90±0.25 t:0.40±0.15
Construction	Marking, Substrate, Resistive, Over coat, Internal terminal, Cu plating, Ni plating, Sn plating	

	Site	Material	Process	Material	Process
Material & Process	Substrate	Glass epoxy resin A	Laminating press	Glass epoxy resin B	Laminating press
	Resistive	Metal foil	Laminating press	Metal foil	Laminating press
	Over coat	Resin	Thick film printing/curing	Resin	Thick film printing/curing
	Internal terminal	Silver(Ag)+Resin	Thick film printing/curing	Silver(Ag)+Resin	Thick film printing/curing
	Cu plating	Cu	Barrel plating	Cu	Barrel plating
	Ni plating	Ni	Barrel plating	Ni	Barrel plating
	Sn plating	Sn	Barrel plating	Sn	Barrel plating
	Marking	—	Laser Marking	—	Laser Marking
Characteristics	Rated power	4W (Rated terminal part temperature 90 degC)		4W (Rated terminal part temperature 90 degC)	
	Resistance range	F class : 5mΩ ≦R≦220mΩ		F class : 5mΩ ≦R≦220mΩ	
		Resistance range	TCR (20deg / +60deg)	Resistance range	TCR (20deg / +60deg)
	F class	5mΩ ≦R<10mΩ	0~+25 ppm/deg	5mΩ ≦R<10mΩ	0~+25 ppm/deg
		10mΩ ≦R≦220mΩ	±25 ppm/deg	10mΩ ≦R≦220mΩ	±25 ppm/deg
Packaging	Code	HJ		HJ	
	Taping	embossed tape(4mm Pitch)		embossed tape(4mm Pitch)	
	Reel	φ180mm(7inch)		φ180mm(7inch)	
	Quantity	2,000pcs/reel		2,000pcs/reel	

Design	Check	Approval	Date	SPECIFICATION No.
			8/Jan./ 2026	ID-2812
			Rev No. G50-02E	ROHM Co.,Ltd.

GMR100HJx

ROHM SEMICONDUCTOR | Products: High Power Metal Plate Shunt Resistors | Type: GMR100HJx Series

Confidential — GMR100 HJx series substrate material change_Comparison table — Different points

Type	GMR100 HJx Series (Present)	GMR100 HJx Series (After change)
Appearance	Top surface (marking side): 10L0; Bottom surface (electrode side)	Top surface (marking side): 10L0; Bottom surface (electrode side); The visibility of the markings has been improved.
Size	6432(2512) : mm(inch)	6432(2512) : mm(inch)
External Dimension : mm	10L0; L:6.40±0.25 W:3.20±0.25 a:2.75±0.25 b:0.90±0.25 t:0.40±0.15	10L0; L:6.40±0.25 W:3.20±0.25 a:2.75±0.25 b:0.90±0.25 t:0.40±0.15
Construction	Marking, Substrate, Resistive, Over coat, Internal terminal, Cu plating, Ni plating, Sn plating	

	Site	Material	Process	Material	Process
Material & Process	Substrate	Glass epoxy resin A	Laminating press	Glass epoxy resin B	Laminating press
	Resistive	Metal foil	Laminating press	Metal foil	Laminating press
	Over coat	Resin	Thick film printing/curing	Resin	Thick film printing/curing
	Internal terminal	Silver(Ag)+Resin	Thick film printing/curing	Silver(Ag)+Resin	Thick film printing/curing
	Cu plating	Cu	Barrel plating	Cu	Barrel plating
	Ni plating	Ni	Barrel plating	Ni	Barrel plating
	Sn plating	Sn	Barrel plating	Sn	Barrel plating
	Marking	—	Laser Marking	—	Laser Marking
Characteristics	Rated power	7W (Rated terminal part temperature 70 degC) 5W (Rated terminal part temperature 110 degC)		7W (Rated terminal part temperature 70 degC) 5W (Rated terminal part temperature 110 degC)	
	Resistance range	F class : 5mΩ ≦R≦220mΩ		F class : 5mΩ ≦R≦220mΩ	
		Resistance range	TCR (20deg / +60deg)	Resistance range	TCR (20deg / +60deg)
	F class	5mΩ ≦R<10mΩ	0~+50 ppm/deg	5mΩ ≦R<10mΩ	0~+50 ppm/deg
		10mΩ ≦R≦220mΩ	±20 ppm/deg	10mΩ ≦R≦220mΩ	±20 ppm/deg
Packaging	Code	HJ		HJ	
	Taping	embossed tape(8mm Pitch)		embossed tape(8mm Pitch)	
	Reel	φ180mm(7inch)		φ180mm(7inch)	
	Quantity	2,000pcs/reel		2,000pcs/reel	

Design	Check	Approval	Date	SPECIFICATION No.
			8/Jan./ 2026	ID-2814
			Rev No. G100J-02E	ROHM Co.,Ltd.

GMR320HJx

ROHM SEMICONDUCTOR | Products: High Power Metal Plate Shunt Resistors | Type: GMR320HJx Series

Confidential — GMR320 HJx series substrate material change_Comparison table — Different points

Type	GMR320 HJx Series (Present)	GMR320 HJx Series (After change)
Appearance	Top surface (marking side): 5L00; Bottom surface (electrode side)	Top surface (marking side): 5L00; Bottom surface (electrode side); The visibility of the markings has been improved.
Size	7142(2817) : mm(inch)	7142(2817) : mm(inch)
External Dimension : mm	10L0; L:7.10±0.25 W:4.20±0.25 a:3.10±0.25 b:0.90±0.25 t:0.40±0.15	10L0; L:7.10±0.25 W:4.20±0.25 a:3.10±0.25 b:0.90±0.25 t:0.40±0.15
Construction	Marking, Substrate, Resistive, Over coat, Internal terminal, Cu plating, Ni plating, Sn plating	

	Site	Material	Process	Material	Process
Material & Process	Substrate	Glass epoxy resin A	Laminating press	Glass epoxy resin B	Laminating press
	Resistive	Metal foil	Laminating press	Metal foil	Laminating press
	Over coat	Resin	Thick film printing/curing	Resin	Thick film printing/curing
	Internal terminal	Silver(Ag)+Resin	Thick film printing/curing	Silver(Ag)+Resin	Thick film printing/curing
	Cu plating	Cu	Barrel plating	Cu	Barrel plating
	Ni plating	Ni	Barrel plating	Ni	Barrel plating
	Sn plating	Sn	Barrel plating	Sn	Barrel plating
	Marking	—	Laser Marking	—	Laser Marking
Characteristics	Rated power	10W (Rated terminal part temperature 70 degC) 7W (Rated terminal part temperature 110 degC)		10W (Rated terminal part temperature 70 degC) 7W (Rated terminal part temperature 110 degC)	
	Resistance range	F class : 5mΩ ≦R≦100mΩ		F class : 5mΩ ≦R≦100mΩ	
		Resistance range	TCR (20deg / +60deg)	Resistance range	TCR (20deg / +60deg)
	F class	5mΩ ≦R<10mΩ	0~+50 ppm/deg	5mΩ ≦R<10mΩ	0~+50 ppm/deg
		10mΩ ≦R≦220mΩ	±25 ppm/deg	10mΩ ≦R≦220mΩ	±25 ppm/deg
Packaging	Code	HJ		HJ	
	Taping	embossed tape(8mm Pitch)		embossed tape(8mm Pitch)	
	Reel	φ180mm(7inch)		φ180mm(7inch)	
	Quantity	2,000pcs/reel		2,000pcs/reel	

Design	Check	Approval	Date	SPECIFICATION No.
			8/Jan./ 2026	ID-2816
			Rev No. G320-01E	ROHM Co.,Ltd.

6. 7026001 Reliability Test Result

GMR50HJx

ROHM SEMICONDUCTOR

信頼性試験結果 Reliability Test Result	ローム株式会社 抵抗器事業部 ROHM CO.,LTD. RESISTOR BUSINESS Div.	作成 Designed 斉藤	承認 Approved 原田

作成日 (DATE)	28/Nov/2025	品名 (Product)	HIGH POWER METAL PLATE SHUNT RESISTORS
管理 No. (Serial No.)	GMR50-B-002	形名.PKG (Type)	GMR50HJ
製造工場 (Factory)	Thailand		

1.試験結果(TEST RESULT)

試験項目 (TEST ITEM)	試験条件 (TEST CONDITION)	準拠規格 (STANDARD)	n[PCS] (Sample QTY.)	Pn (NG QTY.)
寸法(長さ) DIMENSIONS (LENGTH)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
寸法(幅) DIMENSIONS (WIDTH)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
寸法(厚さ) DIMENSIONS (THICKNESS)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
抵抗値(F 級) RESISTANCE (F)	20℃ 65%R. H.	JIS C 5201-1 SEC. 6. 1	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
温度による抵抗値変化 VARIATION OF RESISTANCE WITH TEMPERATURE	+20/+60℃	JIS C 5201-1 SEC. 6. 2	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
過負荷 OVERLOAD	定格電力(RATED POWER)×4.0 倍(TIMES) 時間(TIME) : 5 秒(s)	JIS C 5201-1 SEC. 8. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
はんだ付け性 SOLDERBILITY	本体浸漬(DIPPING AT) : 245℃ 時間(TIME) : 2 秒(s)	JIS C 5201-1 SEC. 11. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
はんだ耐熱性 RESISTANCE TO SOLDERING HEAT	本体浸漬(DIPPING AT) 260℃ 時間(TIME) : 10 秒(s)	JIS C 5201-1 SEC. 11. 2	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
温度急変 RAPID CHANGE OF TEMPERATURE	-55℃～+155℃ 無負荷放置(WITH NO LOAD) 時間(TIME) : 1,000 サイクル(cycles)	JIS C 5201-1 SEC. 10. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
高温高湿(定常) DAMP HEAT, STEADY STATE	85℃ 85%R.H. 無負荷放置(WITH NO LOAD) 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 10. 4	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
90℃での耐久性 ENDURANCE AT 90℃	端子温度(TERMINAL TEMP.) : 90℃ 定格負荷(WITH RATED LOAD) DUTY=1.5h ON－0.5h OFF 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 7. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
170℃での耐久性 ENDURANCE AT 170℃	170℃ 無負荷放置(WITH NO LOAD) 時間(TIME) : 1, 000 時間(h)	JIS C 5201-1 SEC. 7. 3	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
部品の耐溶剤性 RESISTANCE TO SOLVENT	23±5℃ 時間(TIME) : 5 分(min) 溶剤(Solvent) : イソプロピルアルコール (ISOPROPYL ALCOHOL)	JIS C 5201-1 SEC. 11. 3	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
耐プリント板曲げ性 BOND STRENGTH OF THE END FACE PLATING	90mm 支点間支持 (ENDURANCE WITH 90mm WIDTH) たわみ量(DEFLECTION) : 3mm たわみ回数(DEFLECTION TIMES) : 1 回(TIMES)	JIS C 5201-1 SEC. 9. 8	n=10pcs. ×3 抵抗値 (RESISTANCE)	0

2.故障判定基準(CRITERION)

測定項目、条件および故障判定基準：仕様書条件による
MEASUREMENT ITEMS, CONDITIONS AND CRITERIONS: PER SPECIFICATION

3.判定結果(JUDGMENT)

合格
OK

GMR100HJx

ROHM SEMICONDUCTOR

信頼性試験結果 Reliability Test Result	ローム株式会社 抵抗器事業部 ROHM CO.,LTD. RESISTOR BUSINESS Div.	作成 Designed 斉藤	承認 Approved 原田

作成日 (DATE)	28/Nov/2025	品名 (Product)	HIGH POWER METAL PLATE SHUNT RESISTORS
管理 No. (Serial No.)	GMR100J-B-003	形名.PKG (Type)	GMR100HJ
製造工場 (Factory)	Thailand		

1.試験結果(TEST RESULT)

試験項目 (TEST ITEM)	試験条件 (TEST CONDITION)	準拠規格 (STANDARD)	n[PCS] (Sample QTY.)	Pn (NG QTY.)
寸法(長さ) DIMENSIONS (LENGTH)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
寸法(幅) DIMENSIONS (WIDTH)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
寸法(厚さ) DIMENSIONS (THICKNESS)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
抵抗値(F 級) RESISTANCE (F)	20℃ 65%R. H.	JIS C 5201-1 SEC. 5. 6	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
温度による抵抗値変化 VARIATION OF RESISTANCE WITH TEMPERATURE	+20/+60℃	JIS C 5201-1 SEC. 6. 2	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
過負荷 OVERLOAD	定格電力(RATED POWER)×4.0 倍(TIMES) 時間(TIME) : 5 秒(s)	JIS C 5201-1 SEC. 8. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
はんだ付け性 SOLDERABILITY	本体浸漬(DIPPING AT) 245℃ 時間(TIME) : 2 秒(s)	JIS C 5201-1 SEC. 11. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
はんだ耐熱性 RESISTANCE TO SOLDERING HEAT	本体浸漬(DIPPING AT) 260℃ 時間(TIME) : 10 秒(s)	JIS C 5201-1 SEC. 11. 2	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
温度急変 RAPID CHANGE OF TEMPERATURE	-55℃～+155℃ 無負荷放置(WITH NO LOAD) 時間(TIME) : 1,000 サイクル(cycles)	JIS C 5201-1 SEC. 10. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
高温高湿(定常) (DAMP HEAT, STEADY STATE)	85℃ 85%R.H. 無負荷放置(WITH NO LOAD) 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 10. 4	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
110℃での耐久性 ENDURANCE AT 110℃	端子温度(TERMINAL TEMP.) : 110℃ 定格負荷(WITH RATED LOAD) DUTY=1.5h ON－0.5h OFF 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 7. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
70℃での耐久性 ENDURANCE AT 70℃	端子温度(TERMINAL TEMP.) : 70℃ 定格負荷(WITH RATED LOAD) DUTY=1.5h ON－0.5h OFF 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 7. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
170℃での耐久性 ENDURANCE AT 170℃	170℃ 無負荷放置(WITH NO LOAD) 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 7. 3	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
部品の耐溶剤性 RESISTANCE TO SOLVENT	23±5℃ 時間(TIME) : 5 分(min) 溶剤(Solvent) : イソプロピルアルコール (ISOPROPYL ALCOHOL)	JIS C 5201-1 SEC. 11. 3	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
耐プリント板曲げ性 BEND STRENGTH OF THE END FACE PLATING	90mm 支点間支持 (ENDURANCE WITH 90mm WIDTH) たわみ量(DEFLECTION) : 3mm たわみ回数(DEFLECTION TIMES) : 1 回(TIMES)	JIS C 5201-1 SEC. 9. 8	n=10pcs. ×3 抵抗値 (RESISTANCE)	0

2.故障判定基準(CRITERION)

測定項目、条件および故障判定基準：仕様書条件による
MEASUREMENT ITEMS, CONDITIONS AND CRITERIONS: PER SPECIFICATION

3.判定結果(JUDGMENT)

合格
OK

GMR320HJx

ROHM SEMICONDUCTOR

信頼性試験結果 Reliability Test Result	ローム株式会社 抵抗器事業部 ROHM CO.,LTD. RESISTOR BUSINESS Div.	作成 Designed 斉藤	承認 Approved 原田

作成日 (DATE)	28/Nov/2025	品名 (Product)	HIGH POWER METAL PLATE SHUNT RESISTORS
管理 No. (Serial No.)	GMR320-B-001	形名.PKG (Type)	GMR320HJ
製造工場 (Factory)	Thailand		

1.試験結果(TEST RESULT)

試験項目 (TEST ITEM)	試験条件 (TEST CONDITION)	準拠規格 (STANDARD)	n[PCS] (Sample QTY.)	Pn (NG QTY.)
寸法(長さ) DIMENSIONS (LENGTH)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
寸法(幅) DIMENSIONS (WIDTH)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
寸法(厚さ) DIMENSIONS (THICKNESS)	マイクロメーター(MICROMETER)	JIS C 5201-1 SEC. 9. 2	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
抵抗値(F 級) RESISTANCE (F)	20℃ 65%R. H.	JIS C 5201-1 SEC. 5. 6	n=20pcs. ×3 抵抗値 (RESISTANCE)	0
温度による抵抗値変化 VARIATION OF RESISTANCE WITH TEMPERATURE	+20/+60℃	JIS C 5201-1 SEC. 6. 2	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
過負荷 OVERLOAD	定格電力(RATED POWER)×4.0 倍(TIMES) 時間(TIME) : 5 秒(s)	JIS C 5201-1 SEC. 8. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
はんだ付け性 SOLDERABILITY	本体浸漬(DIPPING AT) : 245℃ 時間(TIME) : 2 秒(s)	JIS C 5201-1 SEC. 11. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
はんだ耐熱性 RESISTANCE TO SOLDERING HEAT	本体浸漬(DIPPING AT) 260℃ 時間(TIME) : 10 秒(s)	JIS C 5201-1 SEC. 11. 2	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
温度急変 RAPID CHANGE OF TEMPERATURE	-55℃～+155℃ 無負荷放置(WITH NO LOAD) 時間(TIME) : 1,000 サイクル(cycles)	JIS C 5201-1 SEC. 10. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
高温高湿(定常) DAMP HEAT, STEADY STATE	85℃ 85%R.H. 無負荷放置(WITH NO LOAD) 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 10. 5	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
110℃での耐久性 ENDURANCE AT 110℃	端子温度(TERMINAL TEMP.) : 110℃ 定格負荷(WITH RATED LOAD) DUTY=1.5h ON－0.5h OFF 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 7. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
70℃での耐久性 ENDURANCE AT 70℃	端子温度(TERMINAL TEMP.) : 70℃ 定格負荷(WITH RATED LOAD) DUTY=1.5h ON－0.5h OFF 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 7. 1	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
170℃での耐久性 ENDURANCE AT 170℃	170℃ 無負荷放置(WITH NO LOAD) 時間(TIME) : 1,000 時間(h)	JIS C 5201-1 SEC. 7. 3	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
部品の耐溶剤性 COMPONENT SOLVENT RESISTANCE	23±5℃ 時間(TIME) : 5 分(min) 溶剤(Solvent) : イソプロピルアルコール (ISOPROPYL ALCOHOL)	JIS C 5201-1 SEC. 11. 3	n=10pcs. ×3 抵抗値 (RESISTANCE)	0
耐プリント板曲げ性 BEND STRENGTH OF THE END FACE PLATING	90mm 支点間支持 (ENDURANCE WITH 90mm WIDTH) たわみ量(DEFLECTION) : 3mm たわみ回数(DEFLECTION TIMES) : 1 回(TIMES)	JIS C 5201-1 SEC. 9. 8	n=10pcs. ×3 抵抗値 (RESISTANCE)	0

2.故障判定基準(CRITERION)

測定項目、条件および故障判定基準：仕様書条件による
MEASUREMENT ITEMS, CONDITIONS AND CRITERIONS: PER SPECIFICATION

3.判定結果(JUDGMENT)

合格
OK

Electronics for the Future

ROHM Co.,Ltd.

No.	ローム社外形名（変更ありません） ROHM Catalog Part Number
1	GMR100HJAAFD
2	GMR100HJAFT
3	GMR100HJBAFA
4	GMR100HJBAFB
5	GMR100HJBDM
6	GMR100HJBFA
7	GMR100HJBFC
8	GMR100HJBFE
9	GMR100HJBFH
10	GMR100HJBFI
11	GMR100HJBFJ
12	GMR100HJBFM
13	GMR100HJBFO
14	GMR100HJBFQ
15	GMR100HJBFS
16	GMR100HJBFT
17	GMR100HJBFV
18	GMR100HJCFA
19	GMR100HJCFH
20	GMR100HJCFI
21	GMR320HJAAFD
22	GMR320HJBFA
23	GMR320HJCFA
24	GMR50HJAAFD
25	GMR50HJBFA
26	GMR50HJBFE
27	GMR50HJBFG
28	GMR50HJBFH
29	GMR50HJBFI
30	GMR50HJBFK
31	GMR50HJBFM